

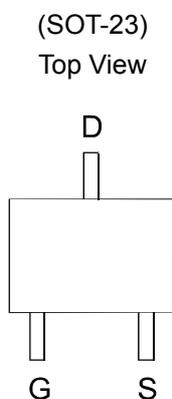
## N-Channel 20V(D-S) MOSFET

### GENERAL DESCRIPTION

The IT2302 is the N-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and low in-line power loss that are needed in a very small outline surface mount package.

### PIN CONFIGURATION

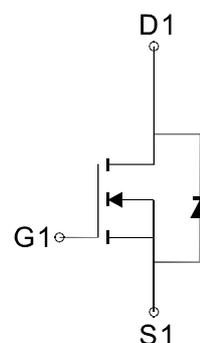


### FEATURES

- $R_{DS(ON)} \leq 85m\Omega @ V_{GS}=4.5V$
- $R_{DS(ON)} \leq 115m\Omega @ V_{GS}=2.5V$
- $R_{DS(ON)} \leq 130m\Omega @ V_{GS}=1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

### APPLICATIONS

- Power Management in Notebook
- Portable Equipment
- Load Switch
- DSC



N-Channel MOSFET

### Absolute Maximum Ratings ( $T_A=25^\circ C$ Unless Otherwise Noted)

Parameter	Symbol	Maximum Ratings	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	$T_A=25^\circ C$	3.2
		$T_A=70^\circ C$	2.6
Pulsed Drain Current	$I_{DM}$	12.8	A
Maximum Power Dissipation	$P_D$	$T_A=25^\circ C$	1.4
		$T_A=70^\circ C$	0.9
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Maximum Junction-to-Ambient	$R_{thJA}$	90	$^\circ C/W$

\*The device mounted on  $1in^2$  FR4 board with 2 oz copper

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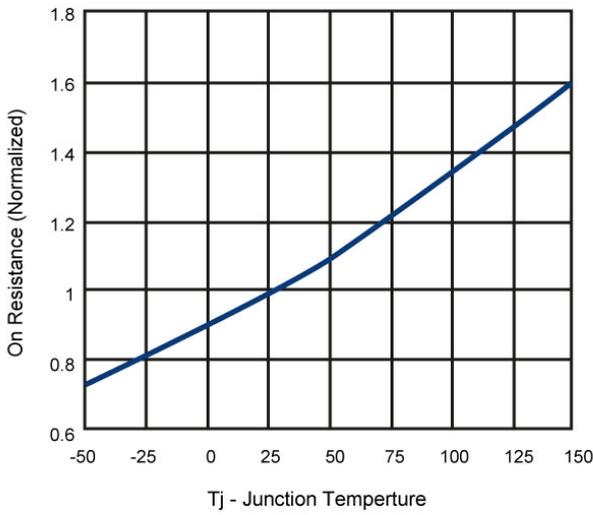
### Electrical Characteristics ( $T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu A$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu A$	0.6		1.2	
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 8V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	$\mu A$
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=2.8A$		55	85	m $\Omega$
		$V_{GS}=2.5V, I_D=2.5A$		65	115	
		$V_{GS}=1.8V, I_D=2.2A$		80	130	
$V_{SD}$	Diode Forward Voltage	$I_S=1A, V_{GS}=0V$		0.75	1.2	V
<b>DYNAMIC PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V, I_D=2.8A$		9		nC
$Q_{gs}$	Gate-Source Charge			2.2		
$Q_{gd}$	Gate-Drain Charge			3		
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, f=1MHz$		450		pF
$C_{oss}$	Output Capacitance			72		
$C_{rss}$	Reverse Transfer Capacitance			22		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=10V, R_L=10\ \Omega$ $V_{GEN}=4.5\ \Omega, R_G=6\ \Omega$		9		ns
$t_r$	Rise Time			23		
$t_{d(off)}$	Turn-Off Delay Time			38		
$t_f$	Fall Time			3		

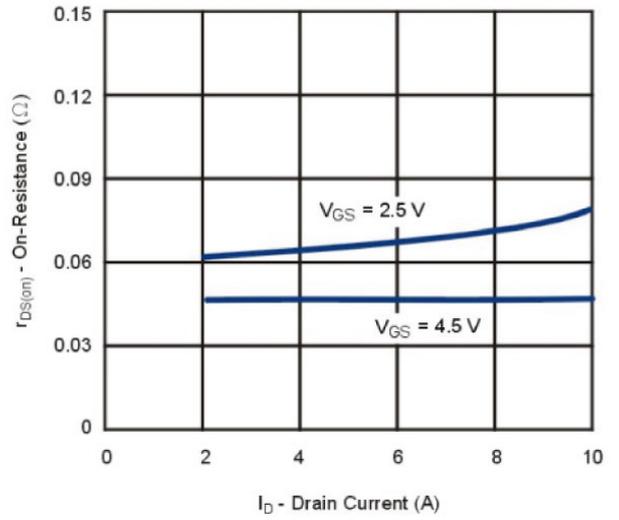
Notes: a. Pulse test; pulse width  $\leq 380\ \mu s$ , duty cycle  $\leq 2\%$

## N-Channel 20V(D-S) MOSFET Typical Characteristics (T<sub>J</sub> = 25°C Noted)

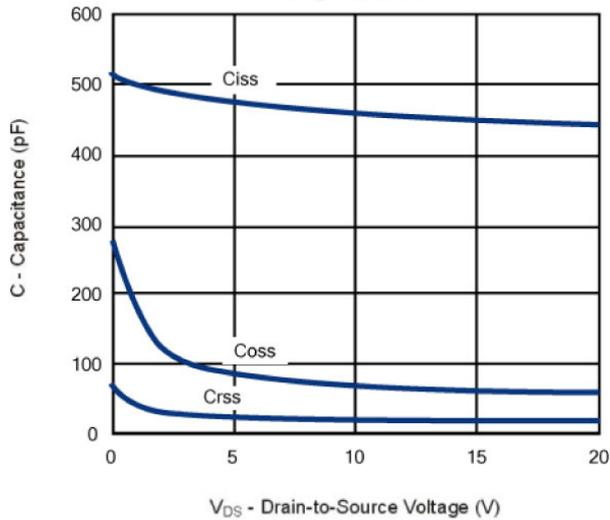
On Resistance vs. Junction Temperature



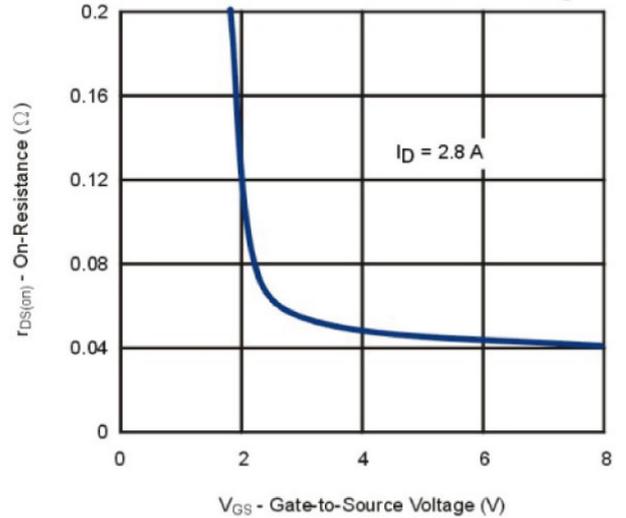
On-Resistance vs. Drain Current



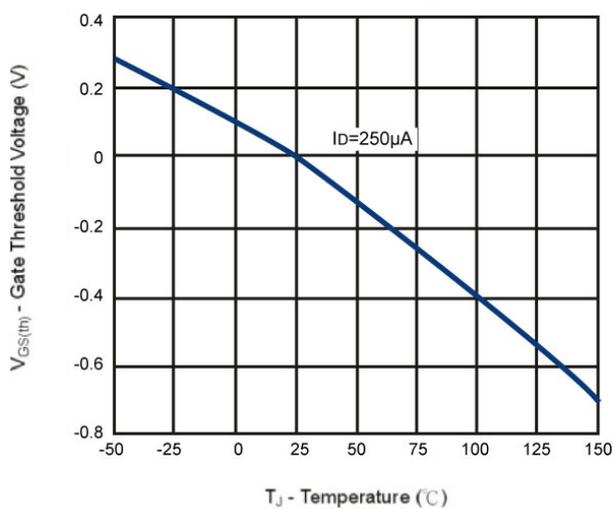
Capacitance



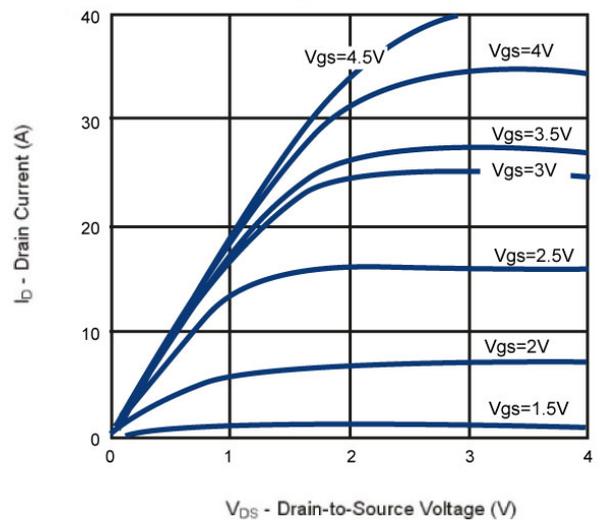
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

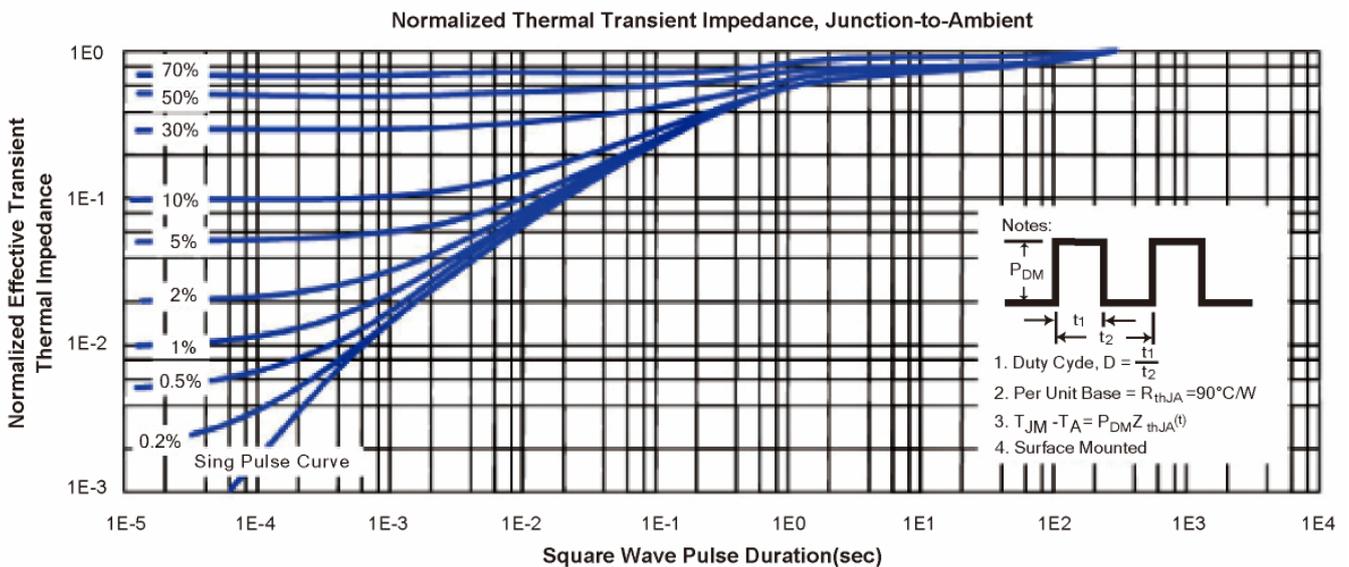
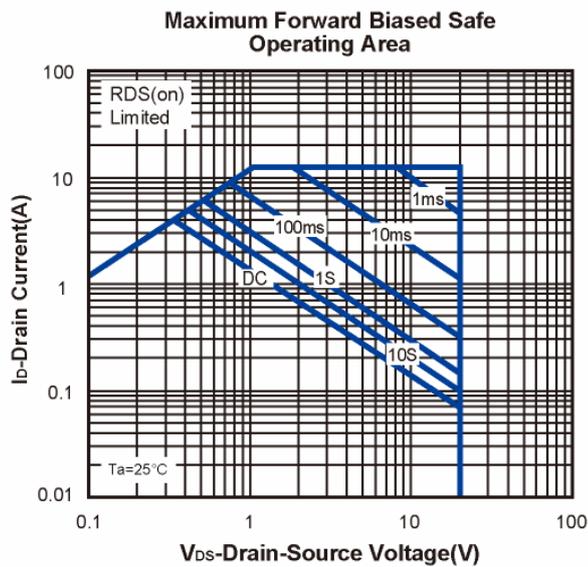
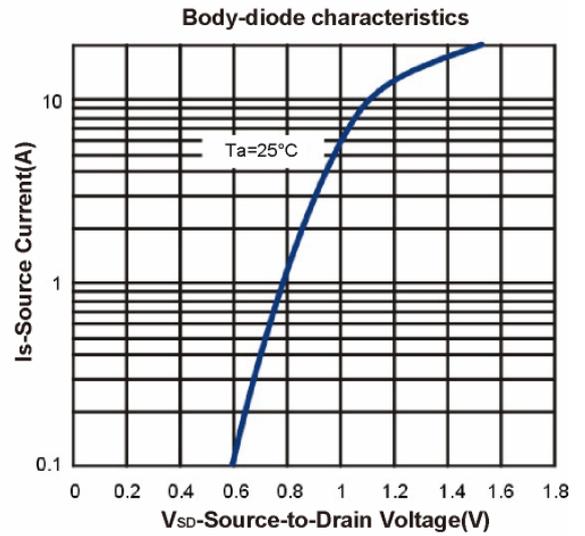
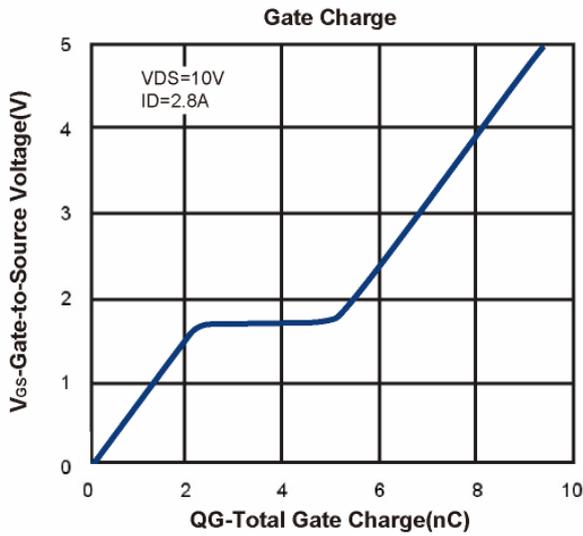


On-Region Characteristics



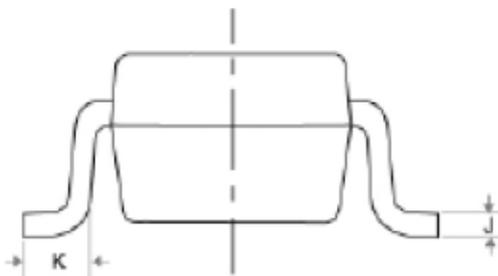
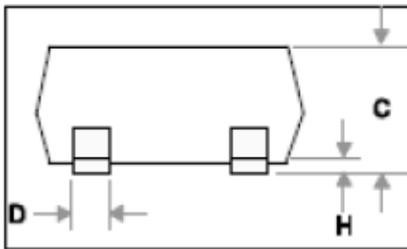
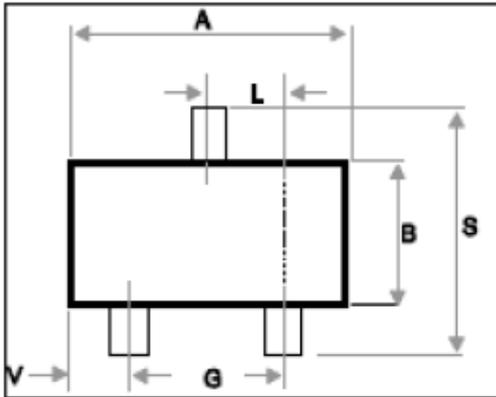
## N-Channel 20V(D-S) MOSFET

Typical Characteristics (T<sub>J</sub> = 25°C Noted)



N-Channel 20V(D-S) MOSFET

SOT-23 Package Outline



Symbol	MILLIMETERS (mm)	
	MIN	MAX
A	2.800	3.000
B	1.250	1.350
C	0.900	1.100
D	0.350	0.50
G	1.800	2.000
H	0.000	0.100
J	0.090	0.150
K	0.200	0.450
L	0.950TYP	
S	2.250	2.550
V	0.550	0.600